Advance Information

Power MOSFET

-40 V, 4.2 m Ω , -140 A, Single P-Channel



ON Semiconductor®

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Features

- Small Footprint (5 × 6 mm) for Compact Design
- Low R_{DS}(on) to Minimize Conduction Losses
- NVMFS5A140PLZWF:

Wettable Flank Option for Enhanced Optical Inspection

- AEC-Q101 Qualified and PPAP Capable
- Pb-Free and RoHS compliance

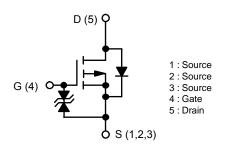
R_DS(on) Max **VDSS** ID Max 4.2 mΩ @ -10 V -40 V -140 A 7.2 mΩ @ -4.5 V

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS at Tj= 25°C unless otherwise noted

(Notes 1, 2, 3, 4)						
Parameter			Symbol	Value	Unit	
Drain to Source Voltage			V_{DSS}	-40	V	
Gate to Source Voltag	Gate to Source Voltage			±20	V	
Continuous Drain Current ^R θJC (Notes 2, 4)	Steady State	T _C = 25°C	ID	-140	А	
Power Dissipation R ₀ JC (Note 2)	State	T _C = 25°C	PD	200	W	
Continuous Drain Current R _θ JA (Notes 2, 3, 4)	Steady State	T _A = 25°C	ID	-20	Α	
Power Dissipation R ₀ JA (Notes 2, 3)	State	T _A = 25°C	PD	3.8	W	
Pulsed Drain Current	PW ≤ 10 μs, duty cycle ≤ 1%		IDP	-560	Α	
Operating Junction and Storage Temperature			Т _Ј , Т _{stg}	-55 to +175	°C	
Source Current (Body Diode)			IS	-140	Α	
Single Pulse Drain to Source Avalanche Energy (L = 1.0 mH, I _{L(pk)} = -29 A)			E _{AS}	420	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C	

ELECTRICAL CONNECTION



P-Channel MOSFET

MARKING DIAGRAM DFN5 (SO-8FL) **AYWZZ**

XXXXXX= Specific Device Code 5A140L(NVMFS5A140PLZ) 140LWF(NVMFS5A140PLZWF)

= Assembly Location

= Year W = Work Week = Lot Traceability

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction to Case Steady State	$R_{\theta JC}$	0.75	°C/W
Junction to Ambient Steady State (Note 3)	$R_{\theta JA}$	39	-0/00

- Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
- Note 2: The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions
- Note 3: Surface mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Note 4: Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

ORDERING INFORMATION

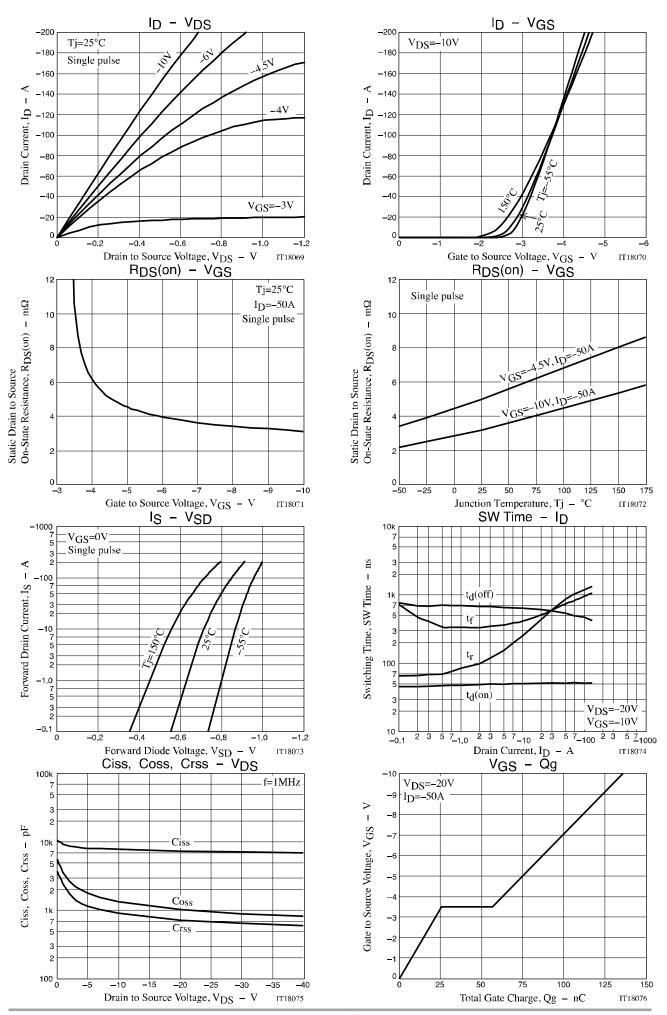
See detailed ordering and shipping information on page 6 of this data sheet.

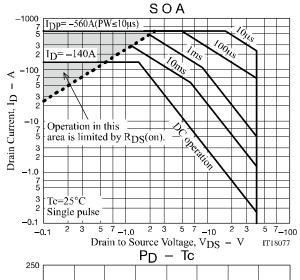
This document contains information on a new product. Specifications and information herein are subject to change without notice.

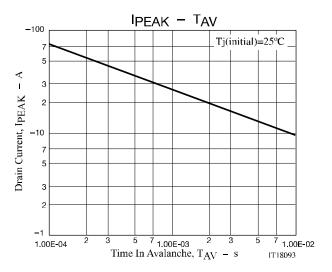
ELECTRICAL CHARACTERISTICS at TJ = 25°C unless otherwise specified (Note 5)

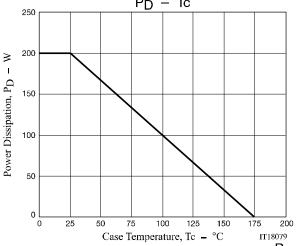
Parameter	Cumbal	Conditions -		Value			l lmit
Parameter	Symbol			min	typ	max	Unit
OFF CHARACTERISTICS							
Drain to Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = -1 mA		-40			V
Zero-Gate Voltage Drain Current	IDSS	$V_{GS} = 0 V$ $V_{DS} = -40 V$	$T_J = 25^{\circ}C$ $T_J = 100^{\circ}C$			-1.0 -100	μA μA
Gate to Source Leakage Current	IGSS	V _{GS} = ±16 V, V _D				±10	μA
ON CHARACTERISTICS (Note	e 6)	•	•	<u>'</u>	<u> </u>		
Gate Threshold Voltage	V _{GS} (th)	$V_{DS} = -10 \text{ V}, I_{D}$	= -1 mA	-1.2		-2.6	V
Design to Occurre On Design to a	D= = (on)	V _{GS} = -10 V	I _D = -50 A		3.2	4.2	mΩ
Drain to Source On Resistance	R _{DS} (on)	V _{GS} = -4.5 V	I _D = -50 A		5.0	7.2	mΩ
Forward Transconductance	9FS	$V_{DS} = -10 \text{ V}, I_{D}$	= -50 A		125		S
CHARGES, CAPACITANCES	& GATE RE	SISTANCE	•		•		
Input Capacitance	C _{iss}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = -20 V			7,400		pF
Output Capacitance	Coss				1,030		
Reverse Transfer Capacitance	C _{rss}				720		
Total Gate Charge	Q _g (tot)	V _{GS} = -10 V, V _{DS} = -20 V, I _D = -50 A			136		nC
Gate to Source Charge	Qgs				26		
Gate to Drain Charge	Q _{gd}				31		
SWITCHING CHARACTERIST	TICS (Note 7)						
Turn-ON Delay Time	t _d (on)				50		
Rise Time	t _r	$V_{GS} = -10 \text{ V}, V_{D}$	$_{0S} = -20 \text{ V},$		860		
Turn-Off Delay Time	t _d (off)	I_D = -50 A, R _G = 50 Ω			540		ns
Fall Time	tf				740		
DRAIN SOURCE DIODE CHA	RACTERIST	ics					
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = -	-50 A		-0.83	-1.5	V
Reverse Recovery Time	t _{rr}	$V_{GS} = 0 V, di/dt$	= 100 A/μs,		108		ns
Reverse Recovery Charge	Q _{rr}	$I_S = -50 \text{ A}$			236		nC

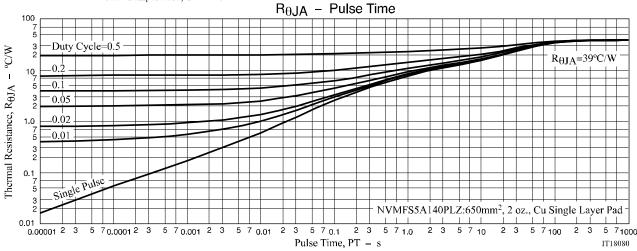
Note 5 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. Note 6 : Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$. Note 7 : Switching characteristics are independent of operating junction temperatures.











PACKAGE DIMENSIONS

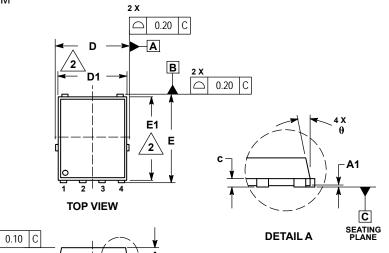
unit: mm

DFN5 5x6, 1.27P (SO-8FL)

> 0.10 C

> > SIDE VIEW

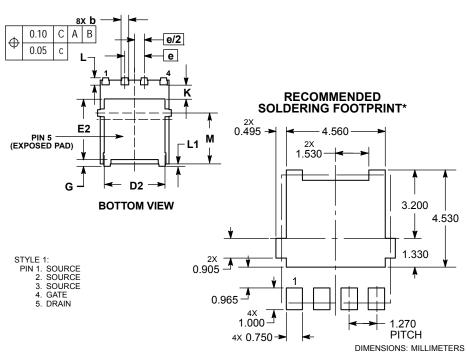
CASE 488AA ISSUE M



DETAIL A

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00		0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
Е	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е	1.27 BSC				
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
М	3.00	3.40	3.80		
θ	0 °		12 °		



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)
NVMFS5A140PLZT1G	5A140L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	1,500 / Tape & Reel
NVMFS5A140PLZWFT1G	MFS5A140PLZWFT1G 140LWF		1,5007 Tape & Reel
NVMFS5A140PLZT3G	5A140L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	5 000 / Tarra & David
NVMFS5A140PLZWFT3G 140LWF		DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	5,000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

Note on usage: Since the NVMFS5A140PLZ is a MOSFET product, please avoid using this device in the vicinity of highly charged objects. Please contact sales for use except the designated application.

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